




E1UHAS-24.576M TR [↗](#)

| | | | |
|--|--|---|---|
| Lead Free  COMPLIANT | RoHS  COMPLIANT | ChinaRoHS  COMPLIANT | REACH SVHC 151 Dec 16, 2013 COMPLIANT |
|--|--|---|---|



ELECTRICAL SPECIFICATIONS

| | |
|--------------------------------------|--|
| Nominal Frequency | 24.576MHz |
| Frequency Tolerance/Stability | ±15ppm at 25°C, ±30ppm over -20°C to +70°C |
| Aging at 25°C | ±5ppm/year Maximum |
| Load Capacitance | Series Resonant |
| Shunt Capacitance | 7pF Maximum |
| Equivalent Series Resistance | 40 Ohms Maximum |
| Mode of Operation | AT-Cut Fundamental |
| Drive Level | 1mWatt Maximum |
| Storage Temperature Range | -40°C to +125°C |
| Insulation Resistance | 500 Megaohms Minimum (Measured at 100Vdc) |

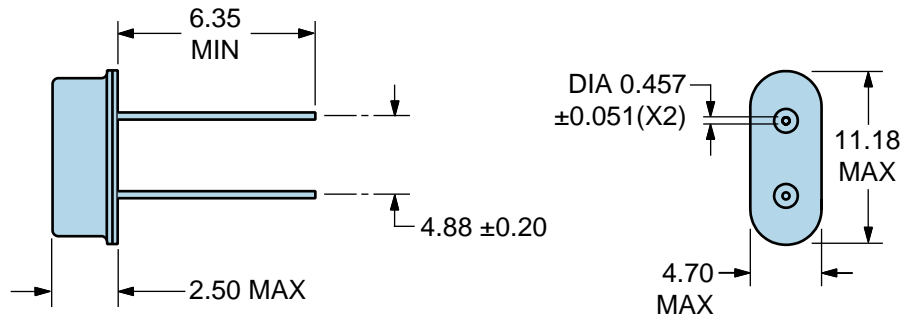
ENVIRONMENTAL & MECHANICAL SPECIFICATIONS

| | |
|-------------------------------------|---|
| ESD Susceptibility | MIL-STD-883, Method 3015, Class 1, HBM: 1500V |
| Fine Leak Test | MIL-STD-883, Method 1014, Condition A |
| Flammability | UL94-V0 |
| Gross Leak Test | MIL-STD-883, Method 1014, Condition C |
| Lead Integrity | MIL-STD-883, Method 2004 |
| Mechanical Shock | MIL-STD-202, Method 213, Condition C |
| Moisture Resistance | MIL-STD-883, Method 1004 |
| Moisture Sensitivity | J-STD-020, MSL1 |
| Resistance to Soldering Heat | MIL-STD-202, Method 210, Condition K |
| Resistance to Solvents | MIL-STD-202, Method 215 |
| Solderability | MIL-STD-883, Method 2003 |
| Temperature Cycling | MIL-STD-883, Method 1010, Condition B |
| Vibration | MIL-STD-883, Method 2007, Condition A |

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MECHANICAL DIMENSIONS (all dimensions in millimeters)

| LINE | MARKING |
|------|---|
| 1 | E24.576M <i>E=Ecliptek Designator</i> |



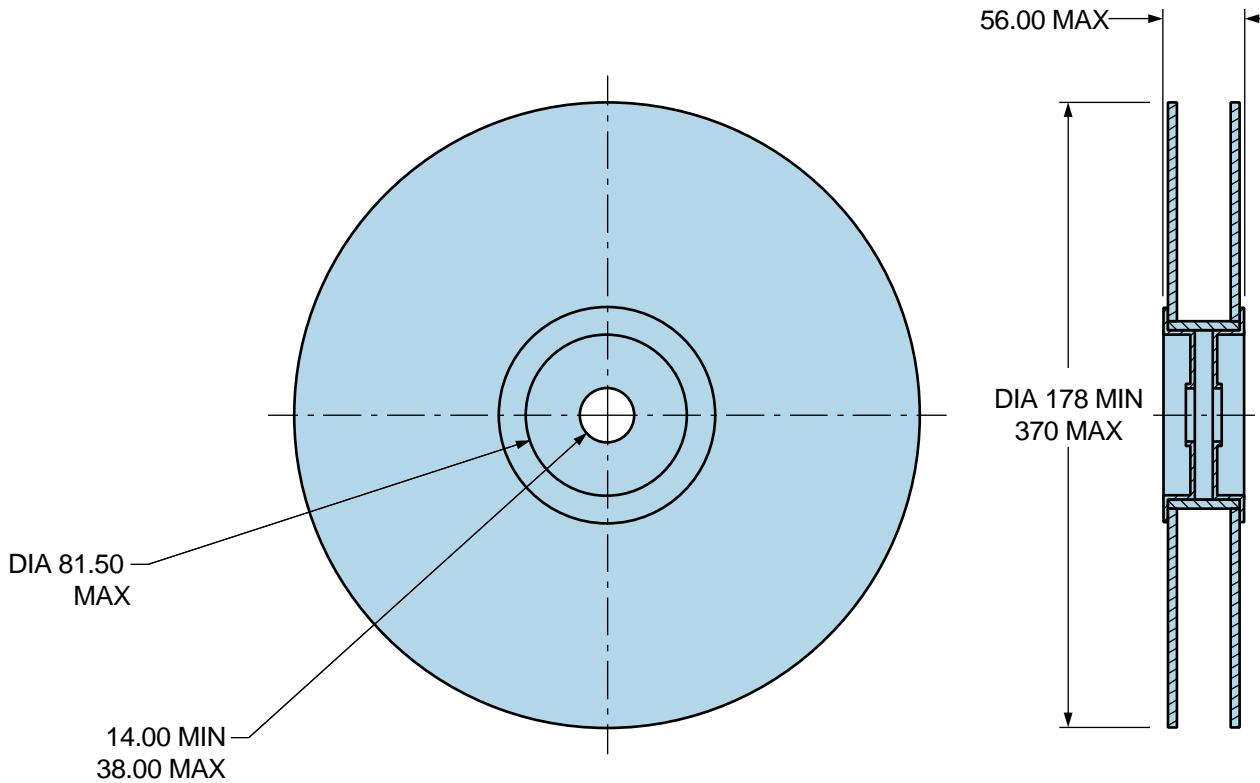
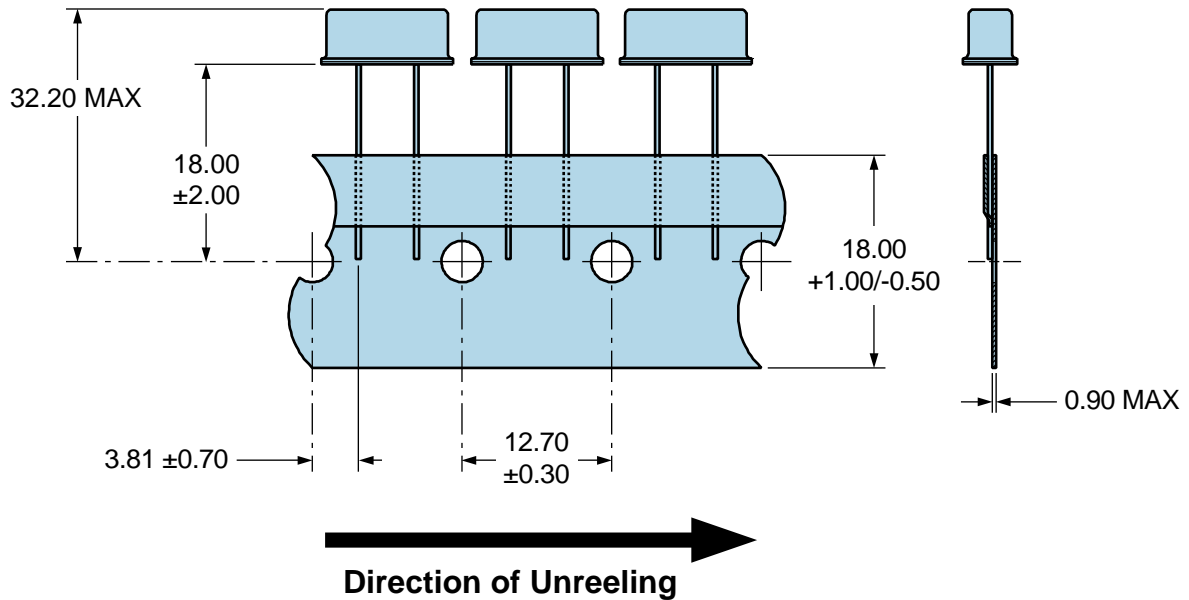
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Tape & Reel Dimensions

Quantity Per Reel: 1,000 units

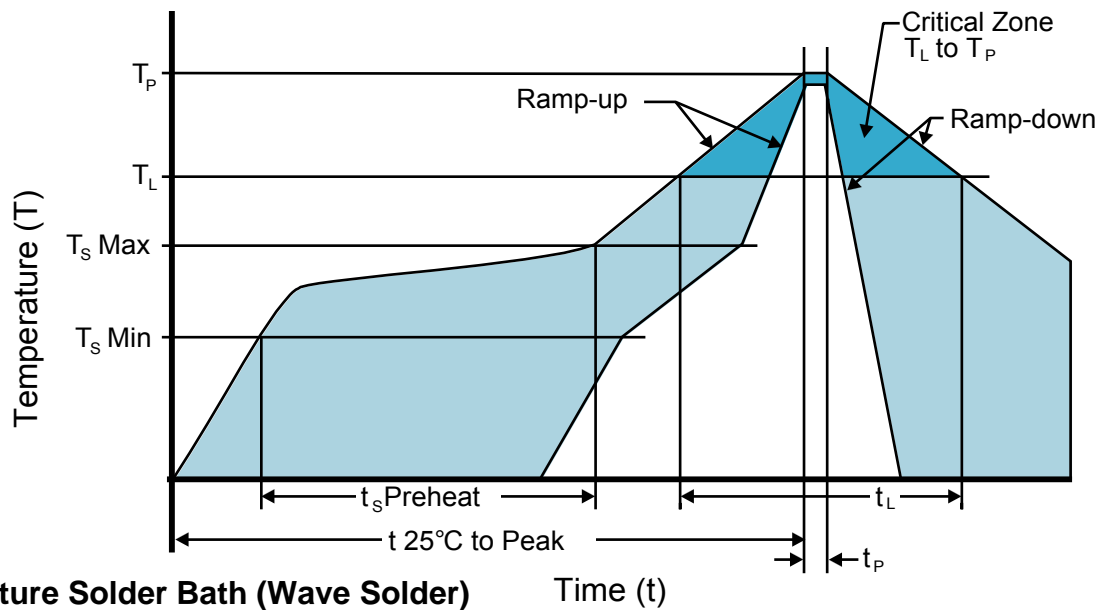
All Dimensions in Millimeters

Compliant to EIA-468



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Recommended Solder Reflow Methods



High Temperature Solder Bath (Wave Solder) Time (t)

Ts MAX to Tl (Ramp-up Rate) 3°C/Second Maximum

Preheat

- Temperature Minimum (Ts MIN) 150°C
 - Temperature Typical (Ts TYP) 175°C
 - Temperature Maximum (Ts MAX) 200°C
 - Time (ts MIN) 60 - 180 Seconds

Ramp-up Rate (Tl to Tp) 3°C/Second Maximum

Time Maintained Above:

- Temperature (Tl) 217°C
 - Time (tL) 60 - 150 Seconds

Peak Temperature (Tp) 260°C Maximum for 10 Seconds Maximum

Target Peak Temperature (Tp Target) 250°C +0/-5°C

Time within 5°C of actual peak (tp) 20 - 40 Seconds

Ramp-down Rate 6°C/Second Maximum

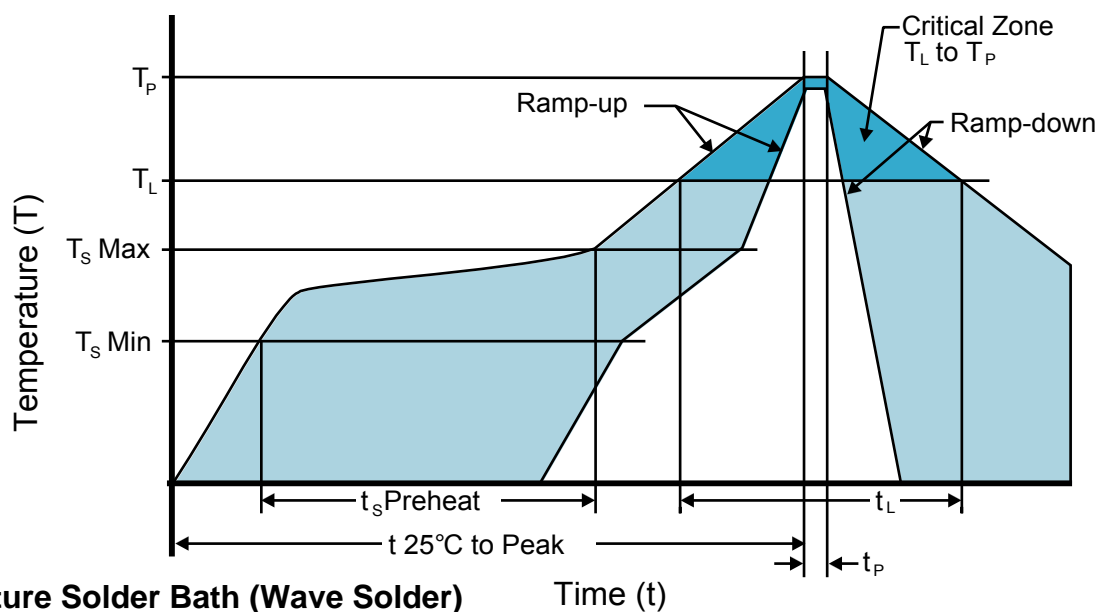
Time 25°C to Peak Temperature (t) 8 Minutes Maximum

Moisture Sensitivity Level Level 1

Additional Notes Temperatures shown are applied to back of PCB board and device leads only.

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Recommended Solder Reflow Methods



Low Temperature Solder Bath (Wave Solder) Time (t)

| | |
|--|--|
| Ts MAX to Tl (Ramp-up Rate) | 5°C/Second Maximum |
| Preheat | |
| - Temperature Minimum (Ts MIN) | N/A |
| - Temperature Typical (Ts TYP) | 150°C |
| - Temperature Maximum (Ts MAX) | N/A |
| - Time (ts MIN) | 30 - 60 Seconds |
| Ramp-up Rate (Tl to Tp) | 5°C/Second Maximum |
| Time Maintained Above: | |
| - Temperature (Tl) | 150°C |
| - Time (tL) | 200 Seconds Maximum |
| Peak Temperature (Tp) | 245°C Maximum |
| Target Peak Temperature (Tp Target) | 245°C Maximum 1 Time / 235°C Maximum 2 Times |
| Time within 5°C of actual peak (tp) | 5 Seconds Maximum 1 Time / 15 Seconds Maximum 2 Times |
| Ramp-down Rate | 5°C/Second Maximum |
| Time 25°C to Peak Temperature (t) | N/A |
| Moisture Sensitivity Level | Level 1 |
| Additional Notes | Temperatures shown are applied to back of PCB board and device leads only. |

Low Temperature Manual Soldering

185°C Maximum for 10 Seconds Maximum, 2 times Maximum. (Temperatures shown are applied to back of PCB board and device leads only.)

High Temperature Manual Soldering

260°C Maximum for 5 Seconds Maximum, 2 times Maximum. (Temperatures shown are applied to back of PCB board and device leads only.)